

Clean version of all pending claims

Initials

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1. (Amended once) A process comprising:
forming a metal interconnect structure onto a substrate, said metal interconnect structure extending above a surface of the substrate;
forming, subsequent to said forming a metal interconnect structure, a carbon-doped oxide (CDO) layer with a first concentration of carbon dopants therein on said substrate and between elements of said metal interconnect structure; and
continuing to form, subsequent to said forming a CDO layer with a first concentration of carbon dopants, said CDO layer further above said metal interconnect structure with a second concentration of carbon dopants therein, wherein the first concentration is different than the second concentration.
2. (Amended once) The process according to Claim 1 further comprising:
forming, subsequent to said continuing to form, the CDO layer further with a third concentration of carbon dopants therein, wherein there is a linear correlation of the concentration of carbon dopants between the first concentration, the second concentration, and the third concentration.
3. (Amended once) The process according to Claim 1 further comprising:

forming the CDO layer further with a third concentration of carbon dopants therein, wherein the first and third concentrations are higher than the second concentration.

4. (Amended once) The process according to Claim 1 further comprising:

forming the CDO layer further with a third concentration of carbon dopants therein, wherein the first and third concentrations are lower than the second concentration.

5. The process according to Claim 1 wherein said first concentration is higher than said second concentration.

6. The process according to Claim 1 wherein said first concentration is lower than said second concentration.

7. (Amended once) A process comprising:

forming a carbon-doped oxide (CDO) layer with a concentration of carbon dopants therein;

wherein the concentration varies substantially linearly from a top of the CDO layer to a bottom of the CDO layer.

8. (Amended once) The process according to Claim 7 wherein the concentration is higher at the top of the CDO layer and lower at the bottom of the CDO layer.

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9. (Amended once) The process according to Claim 7 wherein the concentration is lower at the top of the CDO layer and higher at the bottom of the CDO layer.

10. The process according to Claim 7 wherein the concentration varies between about 1 percent and about 20 percent by atomic mass.

11-23. (Cancelled)

24.
27. (New) An apparatus, comprising:

a carbon-doped oxide (CDO) layer having an interconnection structure disposed within the CDO layer and having a concentration of dopant that varies substantially linearly from a top of the CDO layer to a bottom of the CDO layer.

25.
28. (New) The apparatus of claim *27*, wherein the concentration is higher at the top of the CDO layer than at the bottom of the CDO layer.

26.
29. (New) The apparatus of claim *27*, wherein the concentration is lower at the top of the CDO layer than at the bottom of the CDO layer.

30.
30. (New) An interlayer dielectric comprising:

a carbon-doped oxide (CDO) layer having a first region with a first concentration of carbon dopants therein, a second region disposed on the first region and having a

second concentration of carbon dopants therein, and a third region disposed on the second region and having a third concentration of dopants therein,

wherein the first and third concentrations are higher than the second concentration.

28.

31. (New) An interlayer dielectric comprising:

28.1. a carbon-doped oxide (CDO) layer having a first region with a first concentration of carbon dopants therein, a second region disposed on the first region and having a second concentration of carbon dopants therein, and a third region disposed on the second region and having a third concentration of dopants therein,

wherein the first and third concentrations are lower than the second concentration.

29.

32. (New) An interlayer dielectric comprising:

29.1. a carbon-doped oxide (CDO) layer having a first region with a first concentration of carbon dopants therein, a second region disposed on the first region and having a second concentration of carbon dopants therein, a third region disposed on the second region and having a third concentration of carbon dopants therein, and a fourth region disposed on the third region and having a fourth concentration of carbon dopants therein;

wherein the first and third concentrations are each higher than either of the second and fourth concentrations.

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33. (New) An interlayer dielectric comprising:

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a carbon-doped oxide (CDO) layer having a first region with a first concentration of carbon dopants therein, a second region disposed on the first region and having a second concentration of carbon dopants therein, a third region disposed on the second region and having a third concentration of carbon dopants therein, and a fourth region disposed on the third region and having a fourth concentration of carbon dopants therein; wherein the first and third concentrations are each lower than either of the second and fourth concentrations.

REMARKS

Claims 22-26 were originally inadvertently misnumbered and have been renumbered 19-23 by the Examiner. These claims, as well as claims 11-18, have been cancelled. Seven new claims have been added, numbered 27-33 to avoid any confusion with the previously numbered claims 22-26.

Claims 1, 5-7, 11-13 and 17-19 have been rejected under 35 USC 102(a) as being anticipated by U.S. patent no. 6,251,770 ("Uglow").

Claims 2-4, 8-10, 14-16 and 20-23 have been rejected under 35 USC 102(a) as being anticipated by Uglow, or in the alternative have been rejected under 35 USC 103(a) as being obvious over Uglow.